# SWITCHMODE<sup>™</sup>

# **NPN Bipolar Power Transistor** For Switching Power Supply Applications

The MJE18002G have an applications specific state-of-the-art die designed for use in 220 V line operated Switchmode Power supplies and electronic light ballasts.

### Features

- Improved Efficiency Due to Low Base Drive Requirements:
  - High and Flat DC Current Gain h<sub>FE</sub>
  - Fast Switching
  - No Coil Required in Base Circuit for Turn-Off (No Current Tail)
- Tight Parametric Distributions are Consistent Lot-to-Lot
- Standard TO-220
- These Devices are Pb-Free and are RoHS Compliant\*

### MAXIMUM RATINGS

F	Rating	Symbol	Value	Unit
Collector-Emitter S	V <sub>CEO</sub>	450	Vdc	
Collector-Emitter	Breakdown Voltage	V <sub>CES</sub>	1000	Vdc
Emitter-Base Volta	age	V <sub>EBO</sub>	9.0	Vdc
Collector Current	– Continuous – Peak (Note 1)	I <sub>C</sub> I <sub>CM</sub>	2.0 5.0	Adc
Base Current	– Continuous – Peak (Note 1)	I <sub>B</sub> I <sub>BM</sub>	1.0 2.0	Adc
Total Device Dissipation @ $T_C = 25^{\circ}C$ Derate above 25°C		PD	50 0.4	W W/°C
Operating and Stor	rage Temperature	T <sub>J</sub> , T <sub>stg</sub>	-65 to 150	°C

#### **THERMAL CHARACTERISTICS**

Characteristics	Symbol	Мах	Unit
Thermal Resistance, Junction-to-Case	$R_{\theta JC}$	2.5	°C/W
Thermal Resistance, Junction-to-Ambient	$R_{\theta JA}$	62.5	°C/W
Maximum Lead Temperature for Soldering Purposes 1/8" from Case for 5 Seconds	ΤL	260	°C

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

1. Pulse Test: Pulse Width = 5 ms, Duty Cycle ≤ 10%.



### **ON Semiconductor®**

http://onsemi.com

### POWER TRANSISTOR 2.0 AMPERES **100 VOLTS - 50 WATTS**



#### MARKING DIAGRAM



Α

### **ORDERING INFORMATION**

Device	Package	Shipping
MJE18002G	TO-220 (Pb-Free)	50 Units / Rail

\*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

Y = Year

WW = Work Week

<sup>=</sup> Pb-Free Package G

## **ELECTRICAL CHARACTERISTICS** (T<sub>C</sub> = 25°C unless otherwise noted)

Characteristic			Symbol	Min	Тур	Max	Unit	
OFF CHARACTERISTICS								•
Collector-Emitter Sustainin	g Voltage (I <sub>C</sub> = 100	mA, L = 2	5 mH)	V <sub>CEO(sus)</sub>	450	-	-	Vdc
Collector Cutoff Current (V	<sub>CE</sub> = Rated V <sub>CEO</sub> , I <sub>E</sub>	3 = 0)		I <sub>CEO</sub>	-	-	100	μAdc
Collector Cutoff Current (Vo (Vo	<sub>CE</sub> = Rated V <sub>CES</sub> , V <sub>CE</sub> = 800 V, V <sub>EB</sub> = 0		T <sub>C</sub> = 125°C T <sub>C</sub> = 125°C	I <sub>CES</sub>	_ _ _	- - -	100 500 100	μAdc
Emitter Cutoff Current ( $V_{EB} = 9.0 \text{ Vdc}, I_C = 0$ )				I <sub>EBO</sub>	_	-	100	μAdc
ON CHARACTERISTICS								
Base-Emitter Saturation Vo	oltage (I <sub>C</sub> = 0.4 Ad (I <sub>C</sub> = 1.0 Ad			V <sub>BE(sat)</sub>		0.825 0.92	1.1 1.25	Vdc
Collector–Emitter Saturation ( $I_C = 0.4$ Adc, $I_B = 40$ mA ( $I_C = 1.0$ Adc, $I_B = 0.2$ Ad	.dc)		@ T <sub>C</sub> = 125°C @ T <sub>C</sub> = 125°C	V <sub>CE(sat)</sub>	- - - -	0.2 0.2 0.25 0.3	0.5 0.5 0.5 0.6	Vdc
(I <sub>C</sub> = 1.0 A	Adc, V <sub>CE</sub> = 5.0 Vdc) Adc, V <sub>CE</sub> = 1.0 Vdc) Adc, V <sub>CE</sub> = 1.0 Vdc) nAdc, V <sub>CE</sub> = 5.0 Vdd	)	@ T <sub>C</sub> = 125°C @ T <sub>C</sub> = 125°C @ T <sub>C</sub> = 125°C	h <sub>FE</sub>	14 - 11 6.0 5.0 10	- 27 17 20 8.0 8.0 20	34 - - - - -	_
DYNAMIC CHARACTERIST	TICS							
Current Gain Bandwidth ( $I_C = 0.2 \text{ Adc}, V_{CE} = 10$	Vdc, f = 1.0 MHz)			f <sub>T</sub>	-	13	-	MHz
Output Capacitance $(V_{CB} = 10 \text{ Vdc}, I_E = 0, f$	= 1.0 MHz)			C <sub>ob</sub>	_	35	60	pF
Input Capacitance (V <sub>EB</sub> = 8.0 V)			C <sub>ib</sub>	_	400	600	pF	
Dynamic Saturation:	$I_{\rm C} = 0.4 \rm{A}$	1.0 μs	@ T <sub>C</sub> = 125°C	V <sub>CE(dsat)</sub>		3.5 8.0		Vdc
determined 1.0 μs and 3.0 μs after rising I <sub>B1</sub> reach 0.9 final I <sub>B1</sub>	$I_{B1} = 40 \text{ mA}$ $V_{CC} = 300 \text{ V}$ 3.0	3.0 μs	@ T <sub>C</sub> = 125°C			1.5 3.8		
(see Figure 18)	$I_{\rm C} = 1.0 \rm{A}$	1.0 μs	@ T <sub>C</sub> = 125°C			8.0 14	-	
	I <sub>B1</sub> = 0.2 A V <sub>CC</sub> = 300 V 3.0 μs	3.0 μs	@ T <sub>C</sub> = 125°C			2.0 7.0	-	

2. Proper strike and creepage distance must be provided.

# **ELECTRICAL CHARACTERISTICS** – continued ( $T_C = 25^{\circ}C$ unless otherwise noted)

Characteristic			Symbol	Min	Тур	Max	Unit	
SWITCHING CHARACTERISTICS: Resistive Load (D.C. ≤ 10%, Pulse Width = 20 μs)								
Turn-On Time	$I_{C} = 0.4 \text{ Adc}$ $I_{B1} = 40 \text{ mAdc}$	@ T <sub>C</sub> = 125°C	t <sub>on</sub>		200 130	300 -	ns	
Turn-Off Time	I <sub>B2</sub> = 0.2 Adc V <sub>CC</sub> = 300 V	@ T <sub>C</sub> = 125°C	t <sub>off</sub>		1.2 1.5	2.5 _	μs	
Turn-On Time	I <sub>C</sub> = 1.0 Adc I <sub>B1</sub> = 0.2 Adc	@ T <sub>C</sub> = 125°C	t <sub>on</sub>		85 95	150 -	ns	
Turn-Off Time	I <sub>B2</sub> = 0.5 Adc V <sub>CC</sub> = 300 V	@ T <sub>C</sub> = 125°C	t <sub>off</sub>		1.7 2.1	2.5 _	μs	
	CTERISTICS Inductive Load	(V) = 300 V Voo = 15	V I 000 II)		•	•		

### SWITCHING CHARACTERISTICS: Inductive Load (V<sub>clamp</sub> = 300 V, V<sub>CC</sub> = 15 V, L = 200 $\mu$ H)

Fall Time	$I_{\rm C} = 0.4$ Adc, $I_{\rm B1} = 40$ mAdc,		t <sub>fi</sub>	-	125	200	ns
	$I_{B2} = 0.2 \text{ Adc}$	@ T <sub>C</sub> = 125°C	-11	-	120	-	
Storage Time			t <sub>si</sub>	-	0.7	1.25	μs
-		@ T <sub>C</sub> = 125°C		-	0.8	-	•
Crossover Time			t <sub>c</sub>	-	110	200	ns
		@ T <sub>C</sub> = 125°C		-	110	-	
Fall Time	$I_{\rm C}$ = 1.0 Adc, $I_{\rm B1}$ = 0.2 Adc,		t <sub>fi</sub>	-	110	175	ns
	I <sub>B2</sub> = 0.5 Adc	@ T <sub>C</sub> = 125°C		-	120	-	
Storage Time			t <sub>si</sub>	-	1.7	2.75	μs
		@ T <sub>C</sub> = 125°C		-	2.25	-	
Crossover Time	7		t <sub>c</sub>	-	200	300	ns
		@ T <sub>C</sub> = 125°C		-	250	-	
Fall Time	$I_{\rm C} = 0.4$ Adc, $I_{\rm B1} = 50$ mAdc,		t <sub>fi</sub>	-	140	200	ns
	I <sub>B2</sub> = 50 mAdc	@ T <sub>C</sub> = 125°C		-	185	-	
Storage Time	7		t <sub>si</sub>	-	2.2	3.0	μs
		@ T <sub>C</sub> = 125°C		-	2.5	-	
Crossover Time	7		t <sub>c</sub>	-	140	250	ns
		@ T <sub>C</sub> = 125°C		-	220	-	



#### **TYPICAL STATIC CHARACTERISTICS**

Figure 1. DC Current Gain @ 1 Volt

hFE, DC CURRENT GAIN

Figure 2. DC Current Gain @ 5 Volts



Figure 3. Collector Saturation Region

Figure 4. Collector-Emitter Saturation Voltage







**TYPICAL SWITCHING CHARACTERISTICS** 





 $T_C \le 125^{\circ}C$ 

V<sub>BE(off)</sub> = 0.5 V

-1.5 V

 $I_C/I_B \ge 4$ L<sub>C</sub> = 500 μH

**GUARANTEED SAFE OPERATING AREA INFORMATION** 



Figure 15. Forward Bias Safe Operating Area





Figure 17. Forward Bias Power Derating

There are two limitations on the power handling ability of a transistor: average junction temperature and second breakdown. Safe operating area curves indicate I<sub>C</sub>-V<sub>CE</sub> limits of the transistor that must be observed for reliable operation; i.e., the transistor must not be subjected to greater dissipation than the curves indicate. The data of Figure 15 is based on  $T_C = 25^{\circ}C$ ;  $T_J(pk)$  is variable depending on power level. Second breakdown pulse limits are valid for duty cycles to 10% but must be derated when  $T_C > 25^{\circ}C$ . Second breakdown limitations do not derate the same as thermal limitations. Allowable current at the voltages shown on Figure 15 may be found at any case temperature by using the appropriate curve on Figure 17. T<sub>J</sub>(pk) may be calculated from the data in Figures 20. At any case temperatures, thermal limitations will reduce the power that can be handled to values less the limitations imposed by second breakdown. For inductive loads, high voltage and current must be sustained simultaneously during turn-off with the base to emitter junction reverse biased. The safe level is specified as a reverse biased safe operating area (Figure 16). This rating is verified under clamped conditions so that the device is never subjected to an avalanche mode.











Table 1. Inductive Load Switching Drive Circuit



TYPICAL THERMAL RESPONSE



#### PACKAGE DIMENSIONS

#### TO-220AB CASE 221A-09 ISSUE AF



NOT	ES:
1.	DIMENSIONING AND

 DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.

CONTROLLING DIMENSION: INCH.
DIMENSION Z DEFINES A ZONE WHERE.

3. DIMENSION Z DEFINES A ZONE WHERE ALL BODY AND LEAD IRREGULARITIES ARE ALLOWED.

	INCHES		MILLIN	IETERS
DIM	MIN	MAX	MIN	MAX
Α	0.570	0.620	14.48	15.75
В	0.380	0.405	9.66	10.28
C	0.160	0.190	4.07	4.82
D	0.025	0.035	0.64	0.88
F	0.142	0.161	3.61	4.09
G	0.095	0.105	2.42	2.66
Н	0.110	0.155	2.80	3.93
J	0.014	0.025	0.36	0.64
K	0.500	0.562	12.70	14.27
L	0.045	0.060	1.15	1.52
N	0.190	0.210	4.83	5.33
Q	0.100	0.120	2.54	3.04
R	0.080	0.110	2.04	2.79
S	0.045	0.055	1.15	1.39
Т	0.235	0.255	5.97	6.47
U	0.000	0.050	0.00	1.27
V	0.045		1.15	
Z		0.080		2.04

STYLE 1:

PIN 1. BASE 2. COLLECTOR

3. EMITTER

4. COLLECTOR

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